



## Material Content Data Sheet



<b>Sales Product Name</b>	ESD129-B1-CSP01005 E63			<b>Issued</b>	7. September 2015			
<b>MA#</b>	MA001346974							
<b>Package</b>	SG-WLL-2-2			<b>Weight*</b>	0.04 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.039	92.40	92.40	923936	923936
pad	inorganic material	phosphorus	7723-14-0	0.000	0.13		1339	
	noble metal	gold	7440-57-5	0.000	0.14		1410	
	noble metal	palladium	7440-05-3	0.000	0.88		8788	
	non noble metal	nickel	7440-02-0	0.003	6.45	7.60	64527	76064
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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